

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

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DATASHEET

4 PIN LONG CREEPAGE SOP PHOTOTRANSISTOR PHOTOCOUPLER EL101X-G Series



Features:

- Free halogens compliant
- Current transfer ratio (CTR: $50\sim600\%$ at I_F =5mA, V_{CE} =5V) (CTR: $63\sim320\%$ at I_F =10mA, V_{CE} =5V)
- High isolation voltage between input and output (Viso=5000 V rms)
- Compact 4 Pin SOP with a 2.0 mm profile
- 8mm long creepage distance
- Pb free and RoHS compliant.
- UL approved (No. E214129)
- VDE approved (No. 40028391)
- SEMKO approved
- NEMKO approved
- DEMKO approved
- FIMKO approved

Description

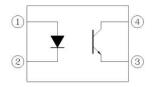
The EL101X-G series devices consist of an infrared emitting diode, optically coupled to a phototransistor detector. Compound use free halogens and $Sb_2O_{3.}$

They are packaged in a 4-pin SOP package

Applications

- Programmable controllers
- System appliances, measuring instruments
- Telecommunication equipments
- Home appliances, such as fan heaters, etc.
- Signal transmission between circuits of different potentials and impedances

Schematic



Pin Configuration

- 1. Anode
- 2. Cathode
- 3. Emitter
- 4. Collector



Absolute Maximum Ratings (Ta=25℃)

	Parameter	Symbol	Rating	Unit
	Forward current	I _F	60	mA
las I	Peak forward current (1us, pulse)	I _{FP}	1.5	А
Input	Reverse voltage	V_{R}	6	V
	Power dissipation	P_D	100	mW
	Power dissipation	P _C	150	mW
	Collector current	I _C	50	mA
Output	Collector-Emitter voltage	V _{CEO}	80	V
	Emitter-Collector voltage	V _{ECO}	7	V
Total Power Dissipation		P _{TOT}	250	mW
Isolation Voltage*1		V _{ISO}	5000	Vrms
Operating Temperature		T _{OPR}	-55 to 110	°C
Storage Temperature		T _{STG}	-55 to 125	°C
Soldering	Temperature*2	T _{SOL}	260	°C

Notes

^{*1} AC for 1 minute, R.H.= $40 \sim 60\%$ R.H. In this test, pins 1, 2 are shorted together, and pins 3, 4 are shorted together.

^{*2} For 10 seconds



Electro-Optical Characteristics (Ta=25℃ unless specified otherwise)

Input

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Forward Voltage	V_{F}	-	1.45	1.5	V	I _F =50mA
Reverse current	I _R	-	-	10	μΑ	$V_R = 6V$
Input capacitance	C _{in}	-	50	-	pF	V = 0, f = 1kHz

Output

<u> </u>						
Parameter	Symbol	Min	Тур.	Max.	Unit	Condition
Collector-Emitter dark current	I _{CEO}	-	-	100	nA	$V_{CE} = 20V$, $I_F = 0mA$
Collector-Emitter breakdown voltage	BV _{CEO}	80	-	-	V	I _C = 0.1mA
Emitter-Collector breakdown voltage	BV_{ECO}	7	-	-	V	I _E = 0.1mA

Transfer Characteristics

Parameter		Symbol	Min	Тур.	Max.	Unit	Condition	
Current Transfer ratio	EL1010		50	-	600			
	EL1017	CTR	80	-	160	%	Ι Ε Α \/ Ε\/	
	EL1018	CIN	130	-	260	70	$I_F = 5mA$, $V_{CE} = 5V$	
	EL1019		200	-	400			
	EL1012	CTR	63	-	125			
	EL1013		100	-	200		$I_F = 10 \text{mA}$, $V_{CE} = 5 \text{V}$	
	EL1014		160	-	320	%		
	EL1012		22	-	-	/6		
	EL1013		34	-	-		$I_F = 1 \text{mA}$, $V_{CE} = 5 \text{V}$	
	EL1014		56	-	-			
Collector-Emitter saturation voltage		$V_{\text{CE(sat)}}$	-	-	0.3	V	$I_F = 10 \text{mA}$, $I_C = 1 \text{mA}$	
Isolation resistance		R _{IO}	5×10 ¹⁰	-	-	Ω	V _{IO} = 500Vdc, 40~60% R.H.	
Floating capacitance		C _{IO}	-	-	1.0	pF	$V_{IO} = 0$, $f = 1MHz$	



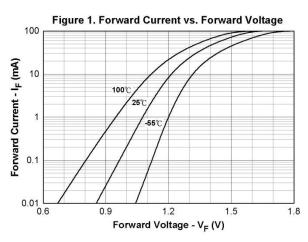
Transfer Characteristics

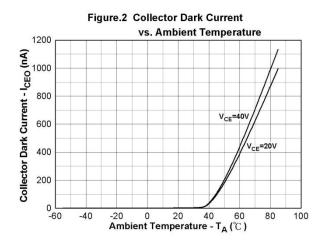
Parameter	Symbol	Min	Тур.	Max.	Unit	Condition
Turn on time	Ton	-	4	-	0	$V_{CE} = 5V, I_{C} = 5mA,$
Turn off time	Toff	-	3	-	μs	$R_L = 100\Omega$
Rise time	t _r	-	2	18	110	$V_{CE} = 5V$, $I_C = 5mA$,
Fall time	t _f	-	3	18	μs	$R_L = 100\Omega$

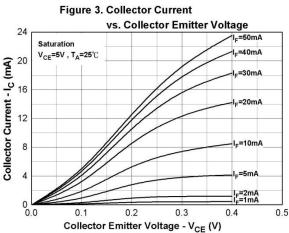
^{*} Typical values at T_a = 25°C

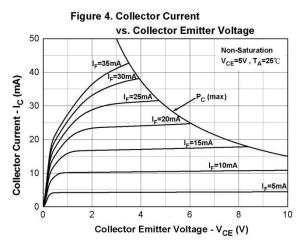


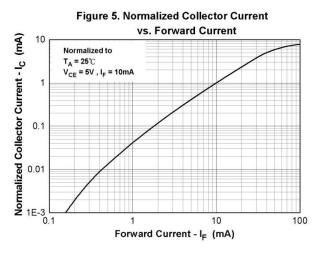
Typical Electro-Optical Characteristics Curves

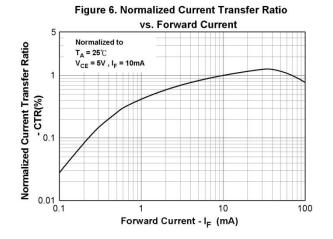


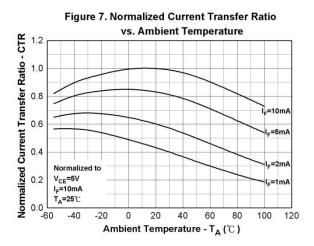


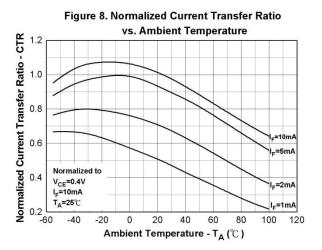


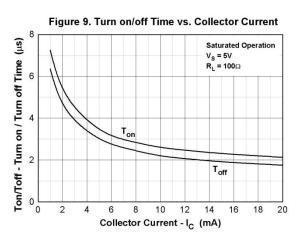


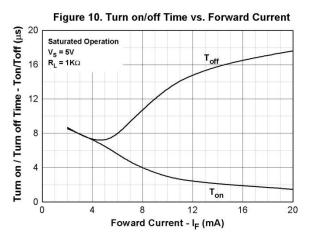


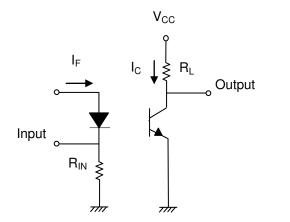












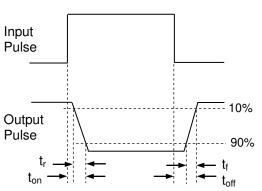


Figure 11. Switching Time Test Circuit & Waveforms



Order Information

Part Number

EL101X(Y)-VG

Note

EL101 = Part No.

X = CTR Rank (0, 2, 3, 4, 7, 8 or 9)

Y = Tape and reel option (TA, TB or none).

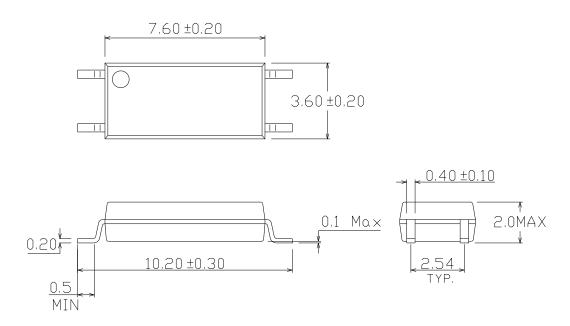
V = VDE safety (optional)

G = Halogens free

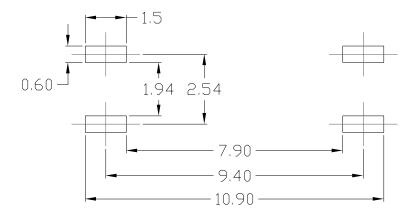
Option	Description	Packing quantity
None	Standard SMD option	100 units per tube
-V	Standard SMD option + VDE	100 units per tube
(TA)	TA Tape & reel option	3000 units per reel
(TB)	TB Tape & reel option	3000 units per reel
(TA)-V	TA Tape & reel option + VDE	3000 units per reel
(TB)-V	TB Tape & reel option + VDE	3000 units per reel



Package Dimension (Dimensions in mm)

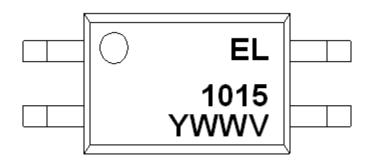


Recommended pad layout for surface mount leadform





Device Marking



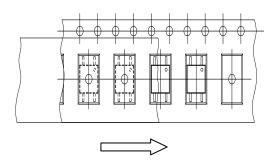
Notes

EL denotes Everlight
1015 denotes Device Number
Y denotes 1 digit Year code
WW denotes 2 digit Week code
V denotes VDE (optional)



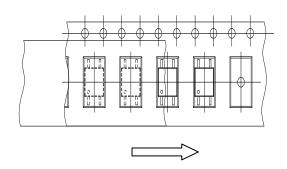
Tape & Reel Packing Specifications

Option TA



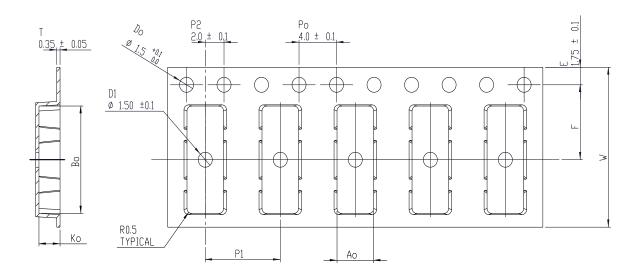
Direction of feed from reel

Option TB



Direction of feed from reel

Tape dimensions



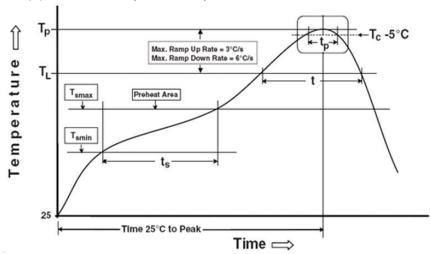
Dimension No.	Ao	Во	Do	D1	E	F
Dimension (mm)	3.9 ± 0.10	10.75 ± 0.10	1.5 + 0.1/-0	1.5 ± 0.10	1.75± 0.10	7.5 ± 0.10
Dimension No.	Ро	P1	P2	Т	w	Ko
			2.0 ± 0.10		16.0 ± 0.30	2.25 ± 0.10



Precautions for Use

1. Soldering Condition

1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



Note:

Reference: IPC/JEDEC J-STD-020D

Preheat

Temperature min (T _{smin})	150 °C
Temperature max (T _{smax})	200°C

 $\begin{array}{ll} \text{Time } (T_{smin} \text{ to } T_{smax}) \text{ } (t_s) & \text{60-120 seconds} \\ \text{Average ramp-up rate } (T_{smax} \text{ to } T_p) & \text{3 °C/second max} \end{array}$

Other

Liquidus Temperature (T _L)	217 °C
Time above Liquidus Temperature (t $_{\rm L}$)	60-100 sec
Peak Temperature (T _P)	260°C

Time within 5 °C of Actual Peak Temperature: T_P - 5 °C 30 s Ramp- Down Rate from Peak Temperature 6 °C /second max.

amp- bown hate from Feak Temperature 6 C/second 1

Time 25°C to peak temperature 8 minutes max.

Reflow times 3 times



DISCLAIMER

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